

Title (en)  
ENCASING ARRANGEMENT FOR A SEMICONDUCTOR COMPONENT

Title (de)  
GEHÄUSEANORDNUNG EINES HALBLEITERBAUSTEINS

Title (fr)  
ENSEMBLE BOITIER D'UN COMPOSANT A SEMI-CONDUCTEUR

Publication  
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Application  
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Abstract (en)  
[origin: WO0145166A2] The invention relates to an encasing arrangement for a semi-conductor component, which comprises a semi-conductor chip (2), a circuit board (8), upon which the semi-conductor component (1) is mounted and a support layer (3), arranged between the semi-conductor chip (2) and the circuit board (8) for rewiring the wiring connectors (11) for the semi-conductor chip (2) on the circuit board (8). The support layer (3) is linked to the circuit board (8), by means of soldered connections (6) and a filler (4) serves to mechanically connect the semi-conductor chip (2) and the soldered connections (6). A metal layer (5) is arranged on the support layer (3), which is connected to soldered connections (6). At least one shaped element (7), made of thermally conductive material, is arranged on the metal layer (5) and is thermally connected to the metal layer (5). The encasing arrangement thus achieves an improved conductivity of the power loss from the incorporated semi-conductor chip (2), which is to be drained off, whereby the desired mechanical properties of the encasing arrangement are maintained.

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